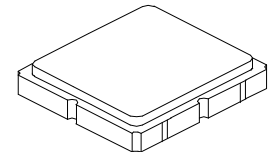


SF2375E

1538.5 MHz
SAW Filter



SM3030-6

- **RF Filter for Mobile Communication Applications**
- **Low Insertion Loss**
- **3.0 x 3.0 x 1.3 mm Surface-Mount Case**
- **No Matching Circuit Required**
- **Complies with Directive 2011/65/EU (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any 2 Terminals	3	VDC
Storage Temperature Range	-40 to +85	°C
Operating Temperature	-40 to +85	°C
Maximum Soldering Profile	265 °C for 10 s	

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C	1		1538.5		MHz
Insertion Loss, 1518 to 1559 MHz	IL			3.4	3.8	dB
Amplitude Ripple, 1518 to 1559 MHz				0.7	1.8	
Attenuation Reference level from 0 dB:						dB
80 to 1442 MHz		1, 2, 3	29	48		
1636 to 2000 MHz			29	45		
Temperature Coefficient of Frequency				-36		Ppm/°C

Case Style	SM3030-6 3 x 3 mm Nominal Footprint
Lid Symbolization (YY=year, WW=week, D=day)	6C <u>Y</u> WWS

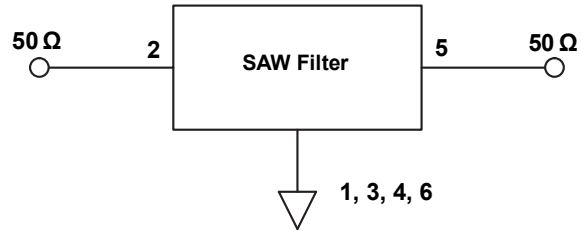
 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

NOTES:

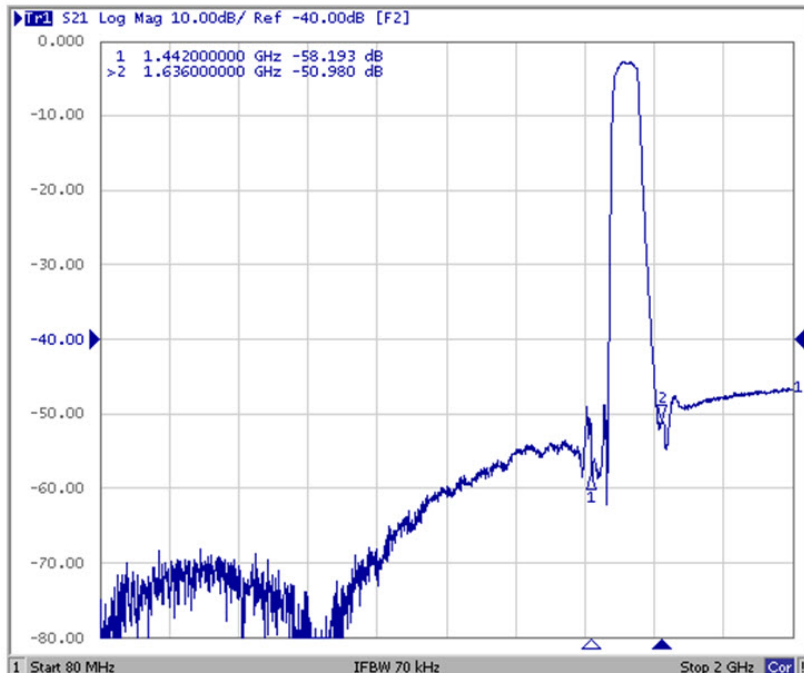
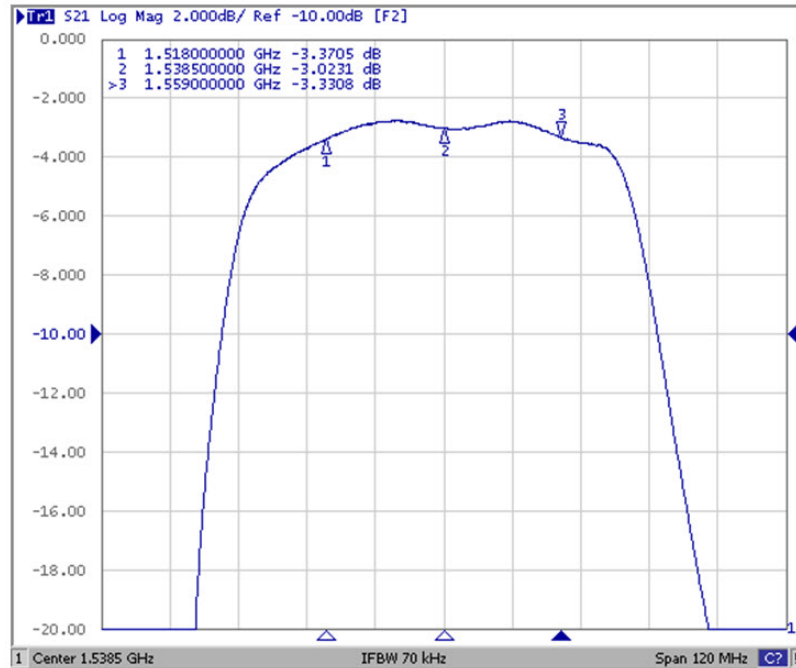
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Electrical Connections

Connection	Terminals
Input	2
Output	5
Ground	All others



Frequency Characteristics

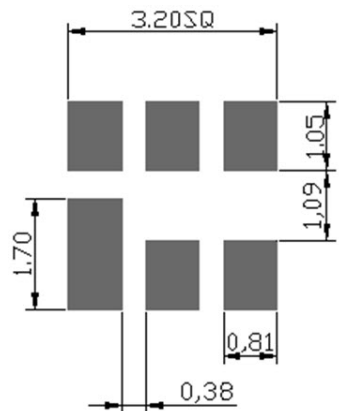
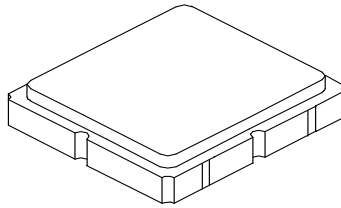


SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint

Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	
P	0.15	0.30	0.45	0.005	0.011	0.017
Q	0.07	0.20	0.36	0.002	0.007	0.014
R	0.62	0.7	0.78	0.024	0.027	0.030

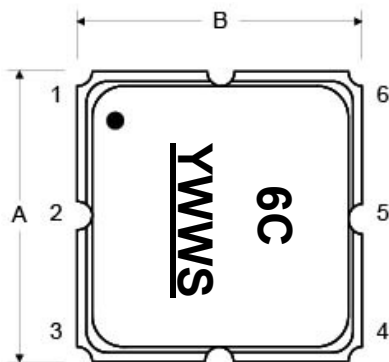


PCB Footprint (mm)

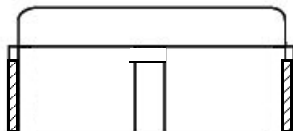
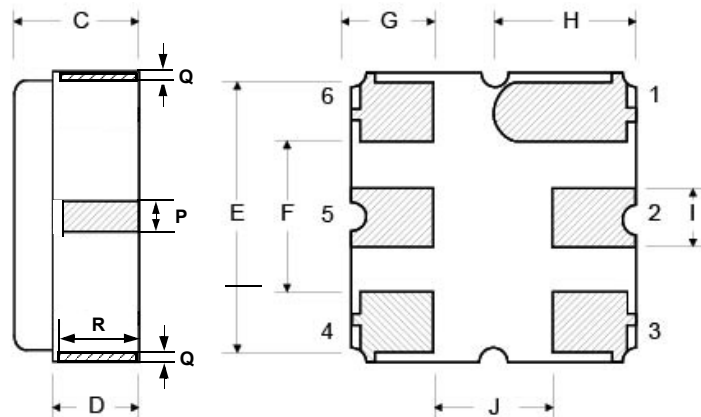
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW

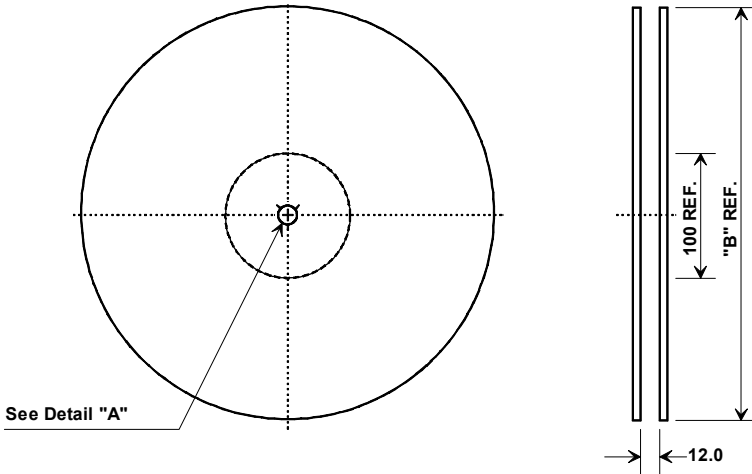


BOTTOM VIEW

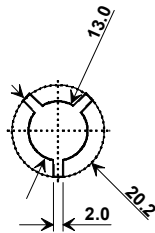


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

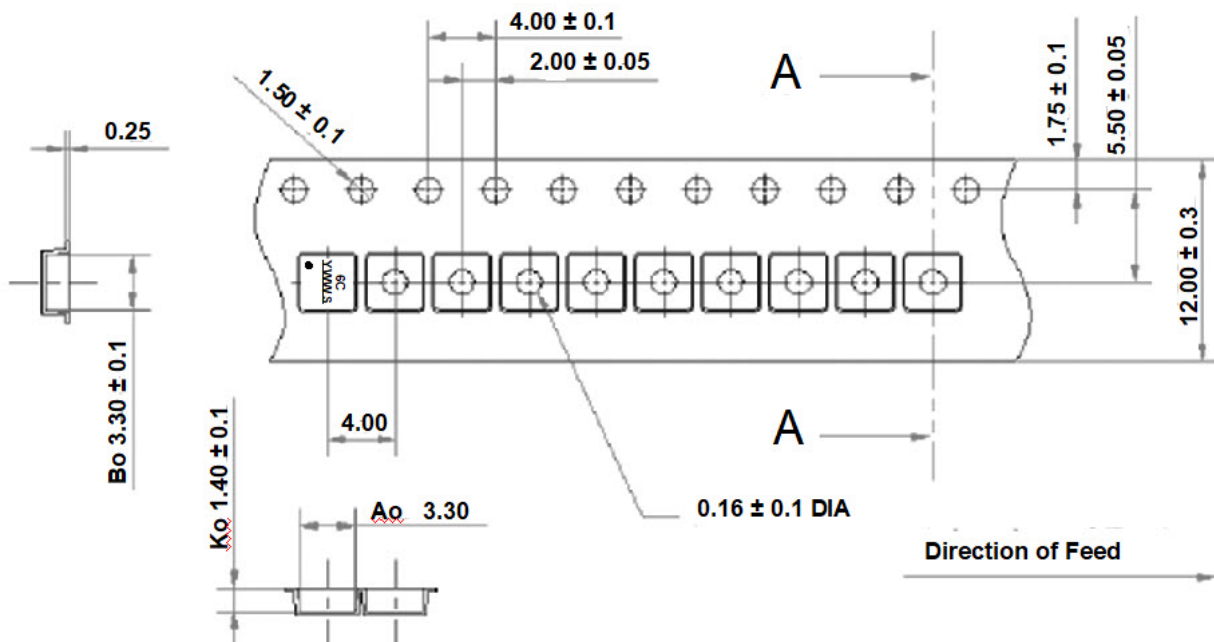


"B" Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.30 mm
Bo	3.30 mm
Ko	1.40 mm
Pitch	4.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

